IJDM Special Issue on Microstructural Mechanics and Damage Mechanics of Materials
Lizhi Sun, Jiann-Wen Woody Ju

▶ To cite this version:

HAL Id: hal-00571151
https://hal.science/hal-00571151
Submitted on 1 Mar 2011

HAL is a multi-disciplinary open access archive for the deposit and dissemination of scientific research documents, whether they are published or not. The documents may come from teaching and research institutions in France or abroad, or from public or private research centers.

L’archive ouverte pluridisciplinaire HAL, est destinée au dépôt et à la diffusion de documents scientifiques de niveau recherche, publiés ou non, émanant des établissements d’enseignement et de recherche français ou étrangers, des laboratoires publics ou privés.
The special issue of International Journal of Damage Mechanics on ‘Microstructural Mechanics and Damage Mechanics of Materials’ is motivated by the Symposium on Recent Advances in Microstructural Mechanics and Damage Mechanics as part of the 2004 International Mechanical Engineering Congress and Exposition (IMECE), held at Anaheim, California, during November 14–19, 2004. The selected papers in this special IJDM journal issue and the next issue encompass a variety of state-of-the-art macromechanical and micromechanical constitutive-damage formulations and computational implementations for multi-phase heterogeneous materials.

We would like to express our gratitude to the authors for contributing their quality work to the special journal issues. All papers have been rigorously peer-reviewed following the standard IJDM review criteria. Furthermore, we express our sincere appreciation to IJDM Chief Editor Professor C.L. Chow for his support of the concept of this special issue.

LIZHI SUN, Associate Professor
Department of Civil and Environmental Engineering
University of California
Irvine, CA 92697-2175

JIANN-WEN WOODY JU, Professor
Department of Civil and Environmental Engineering
University of California
Los Angeles, CA 90095-1593
LIST OF SEVEN PAPERS FOR THE IJDM SPECIAL ISSUE

1. Y. Wei, C.L. Chow, P. Vianco, and E. Fang, “Isothermal Fatigue Damage Model for Lead-free Solder”.

Papers 1–4 appear in vol. 15/2 and papers 5–7 in vol. 15/3.